

## EAST Search History

## EAST Search History (Prior Art)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L10	38674	(embed\$4 encapsula\$5) near3 (component device module IC chip or micro adj circuit microcircuit) same (base sheet film layer insulat\$3 dielectric)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/11/06 17:52
L11	10355	10 and (pcb board motherboard) and (conduct\$4 metal\$3) same (base sheet film layer insulat\$3 dielectric)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/11/06 17:53
L13	5165	11 and (component device module IC chip or micro adj circuit microcircuit) same (opening recess\$3 trench groove)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/11/06 17:54
L15	1508	13 and ((second additional other) with (component device module IC chip or micro adj circuit microcircuit)) same (opening recess\$3 trench groove) same (base sheet film layer insulat\$3 dielectric)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/11/06 17:55
L16	859	15 and (@ad< "20030918" @rlad< "20030918")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/11/06 17:56
L17	604	16 and (base sheet film layer insulat\$3 dielectric) same (polymer glass-fibre FR4 PI polyimide FR5 aramid polytetrafluoroethylene Teflon LCP "liquid crystal polymer" pre-hardened adj binder prepreg)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/11/06 18:03
L18	518	17 and ("438"/\$.ccls. "257"/\$.ccls. "216"/\$.ccls. "174"/\$.ccls. "29"/\$.ccls.)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/11/06 18:05

L19	392	18 and (component device module IC chip or micro adj circuit microcircuit) same (pattern\$5) same (conduct\$4 metal\$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/11/06 18:09
L20	1	(US-20070206366-\$).did.	US-PGPUB	OR	ON	2009/11/06 18:17
L21	1	(US-7513037-\$).did.	USPAT	OR	ON	2009/11/06 18:29
L22	1	(US-6972964-\$).did.	USPAT	OR	ON	2009/11/06 18:36
L23	3	20 21 22	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/11/06 18:47
L24	64	((component device module IC chip or micro adj circuit microcircuit) same (pattern\$5) same (conduct\$4 metal\$3) same (glu\$3 adhesive) same (base sheet film layer insulat\$3 dielectric) same (opening recess \$3 trench groove) same (second additional other)).clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/11/06 18:52
L25	3	((second additional other) adj (component device module IC chip or micro adj circuit microcircuit)) same (pattern\$5) same (conduct\$4 metal\$3) same (glu\$3 adhesive) same (base sheet film layer insulat\$3 dielectric) same (opening recess \$3 trench groove)).clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/11/06 18:54

**EAST Search History (I nterference)**

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L26	2	((second additional other) adj (component device module IC chip or micro adj circuit microcircuit)) same (pattern\$5) same (conduct\$4 metal\$3) same (glu\$3 adhesive) same (base sheet film layer insulat\$3 dielectric) same (opening recess\$3 trench groove)).clm.	USPAT; UPAD	OR	ON	2009/11/06 18:59

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